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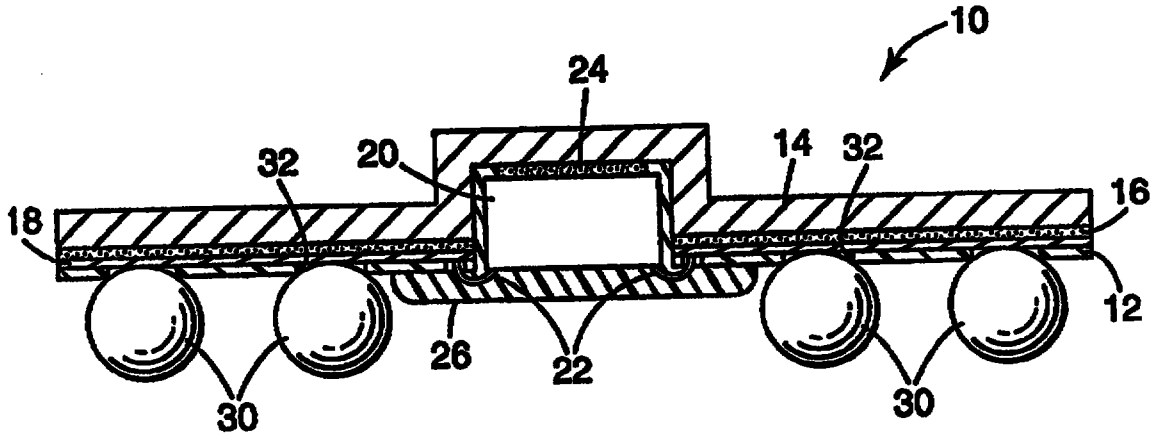
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(54) Title: WIRE BOND TAPE BALL GRID ARRAY PACKAGE



(57) Abstract

A tape ball grid array package reverses the usual attachment of flexible circuitry to a stiffener so that the circuit traces face the stiffener rather than away from the stiffener as is conventional. This construction allows the elimination of a previously necessary solder mask and so reduces the cost to produce the package.